

# Schottky

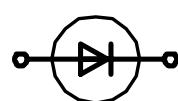
# High Performance Schottky Diode

## Low Loss and Soft Recovery

### Single Diode

$$\begin{aligned}V_{RRM} &= 100 \text{ V} \\I_{FAV} &= 2 \text{ A} \\V_E &= 0.65 \text{ V}\end{aligned}$$

**DSA 2 I 100 SB**      **(S2KAB)**



## **Features / Advantages:**

- Very low Vf
  - Extremely low switching losses
  - Low  $I_{rm}$ -values
  - Improved thermal behaviour
  - High reliability circuit operation
  - Low voltage peaks for reduced protection circuits
  - Low noise switching
  - Low losses

### **Applications:**

- Rectifiers in switch mode power supplies (SMPS)
  - Free wheeling diode in low voltage converters
  - Decoupling diode

## Package:

- Industry standard outline
  - Epoxy meets UL 94V-0
  - RoHS compliant

Symbol		Definition	Conditions	Ratings			
				min.	typ.	max.	Unit
$V_{RRM}$		max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$			100	V
$I_R$		reverse current	$V_R = 100 V$	$T_{VJ} = 25^\circ C$		0.01	mA
			$V_R = 100 V$	$T_{VJ} = 125^\circ C$		5	mA
$V_F$		forward voltage	$I_F = 2 A$	$T_{VJ} = 25^\circ C$		0.79	V
			$I_F = 4 A$			0.87	V
			$I_F = 2 A$	$T_{VJ} = 125^\circ C$		0.65	V
			$I_F = 4 A$			0.75	V
$I_{FAV}$		average forward current	rectangular, $d = 0.5$	$T_L = 125^\circ C$		2	A
$V_{FO}$ $r_F$		threshold voltage slope resistance	} for power loss calculation only	$T_L = 175^\circ C$			V $m\Omega$
$R_{thJL}$		thermal resistance junction to lead*				25	K/W
$T_{VJ}$		virtual junction temperature		-55		175	°C
$P_{tot}$		total power dissipation	$T_L = 25^\circ C$			6	W
$I_{FSM}$		max. forward surge current	$t_p = 10 ms$ (50 Hz), sine	$T_{VJ} = 45^\circ C$		75	A
$C_J$		junction capacitance	$V_R = 5 V$ ; $f = 1 MHz$	$T_{VJ} = 25^\circ C$		85	pF
$E_{AS}$		non-repetitive avalanche energy	$I_{AS} = A$ ; $L = 100 \mu H$	$T_{VJ} = 25^\circ C$		tbd	mJ
$I_{AR}$		repetitive avalanche current	$V_A = 1.5 \cdot V_R$ typ.; $f = 10 kHz$			tbd	A

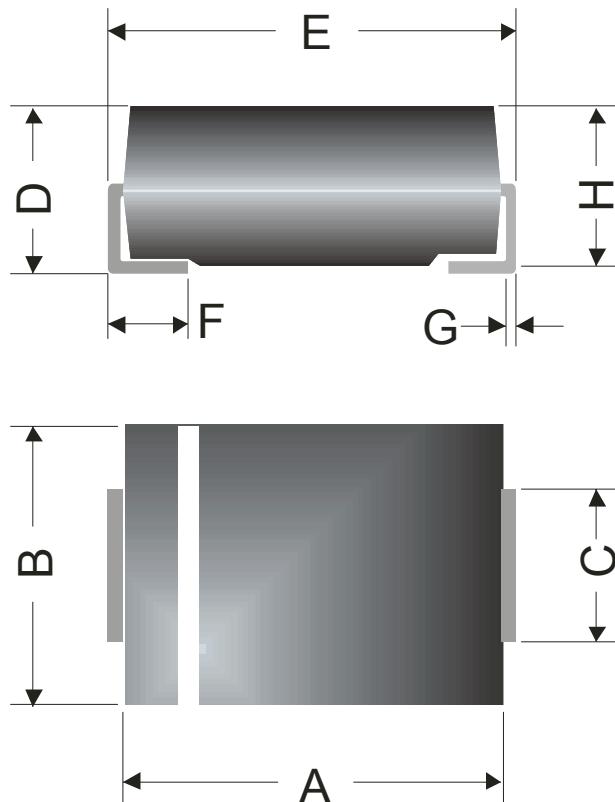
\* mounted on 1 inch square PCB

Symbol	Definition	Conditions	Ratings		
			min.	typ.	max.
$I_{RMS}$	RMS current	per pin*			A
$R_{thJA}$	thermal resistance junction to ambient			70	K/W
$M_D$	mounting torque				Nm
$F_c$	mounting force with clip				N
$T_{stg}$	storage temperature		-55		150 °C
Weight				0.1	g

\*  $I_{RMS}$  is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

### Outlines SMB (DO-214AA)



Dim.	Millimeters		Inches	
	min	max	min	max
A	4.06	4.57	0.160	0.180
B	3.30	3.94	0.130	0.155
C	1.95	2.20	0.077	0.087
D	2.13	2.44	0.084	0.096
E	5.21	5.59	0.205	0.220
F	0.76	1.52	0.030	0.060
G	0.15	0.31	0.006	0.012
H	2.00	2.20	0.079	0.087